

Docket No.: H0498.70130US01

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Serial No.:

Tao Deng 10/763,819

Confirmation No.:

5026

Filed:

January 23, 2004

For:

FABRICATION OF METALLIC MICROSTRUCTURES VIA

EXPOSURE OF PHOTOSENSITIVE COMPOSITION

Examiner:

K. Duda

Art Unit:

1756

Certificate of Mailing Under 37 CFR 1.8(a)

I hereby certify that this paper (along with any paper referred to as being attached or enclosed) is being deposited with the U.S. Postal Service on the date shown below with sufficient postage as First Class Mail, in an envelope addressed to: Mail Stop Issue Fee, Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450.

Dated: 4 11 07

Nellowe Signature

TRANSMITTAL LETTER

Mail Stop Issue Fee Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

Dear Sir:

Enclosed are the following items for filing in connection with the above-referenced Patent Application:

- 1. Amendment After Allowance;
- 2. Part B Issue Fee Transmittal; and
- 3. Return Receipt Postcard.

Our check in the amount of \$1,000.00 covering the required fees. is enclosed. The Director is hereby authorized to charge any deficiency in the fees filed, asserted to be filed or which should have been filed herewith (or with any paper hereafter filed in this application by this firm) to our Deposit Account No. 23/2825, under Docket No. H0498.70130US01. A duplicate copy of this paper is enclosed.

Dated: April 11, 2007

Respectfully submitted,

Timothy J. Oyer Ph.D. Registration No.: 36,628

WOLF, GREENFIELD & SACKS, P.C.

Federal Reserve Plaza 600 Atlantic Avenue

Boston, Massachusetts 02210-2206

(617) 646-8000